TOSHIBA PHOTOCOUPLER IRED & PHOTO-IC

TLP718F

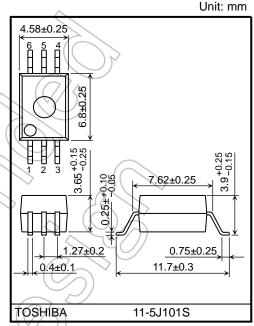
Isolated Bus Drivers
High Speed Line Receivers
Microprocessor System Interfaces

The Toshiba TLP718F consists of an infrared emitting diode and an integrated high-gain, high-speed photodetector. This unit is a 6-pin SDIP. The TLP718F is 50% smaller than the 8-PIN DIP and meets the reinforced insulation class requirements of international safety standards. Therefore the mounting area can be reduced in equipment requiring safety standard certification.

The detector has a totem pole output stage to provide both source and sink driving. The detector IC has an internal shield that provides a guaranteed common-mode transient immunity of 10 kV/ μ s.

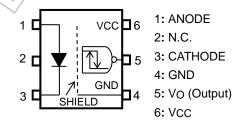
The TLP718F is inverter logic type. For buffer logic type, the TLP715F is in line-up.

- Inverter logic type (totem pole output)
- Guaranteed performance over temperature : -40 to 100°C
- Power supply voltage: 4.5 to 20 V
- Input current: IFHL = 3 mA (max)
- Switching time (tpHL / tpLH): 250 ns (max)
- Common-mode transient immunity: ±10 kV/μs (min)
- Isolation voltage: 5000 Vrms (min)
- UL-recognized: UL 1577, File No.E67349
- cUL-recognized: CSA Component Acceptance Service No.5A
 File No.E67349
- VDE-approved: EN 60747-5-5, EN 62368-1 (Note1)



Weight: 0.26 g (typ.)

Pin Configuration (Top View)



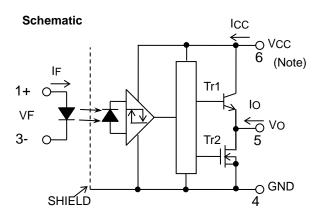
Note 1: When a VDE approved type is needed, please designate the **Option(D4)**.

Construction Mechanical Rating

	10.16 mm pitch TLPXXXF type
Creepage Distance Clearance Insulation Thickness	8.0 mm (min) 8.0 mm (min) 0.4 mm (min)

Truth Table

Input	LED	Tr1	Tr2	Output
Н	ON	OFF	ON	L
L	OFF	ON	OFF	Н



Note: $0.1 \mu F$ bypass capacitor must be connected between pins 6 and 4.

Start of commercial production 2008-12



Absolute Maximum Ratings (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (Ta ≤ 83°C)	lF	20	mA
Forward Current Derating (Ta ≥ 83°C)	ΔΙ _Ε /ΔΤα	-0.48	mA/°C
Peak Transient Forward Current (Note 1)	I _{FPT}	1	A
Reverse Voltage	VR	5	(v)
Input power dissipation	P _D	40	/mW
Input power dissipation derating (Ta ≥ 83°C)	ΔΡ _D /ΔΤα	-0.96	mW/°C
Junction Temperature	Tj	125	°C
Output Current 1 (Ta ≤ 25°C)	lot	25 / -15	mA <
Output Current 2 (Ta ≤ 100°C)	102	13 / -13	mA
Output Voltage	(40)	-0.5 to 20	
Supply Voltage	Vcc	-0.5 to 20	V
Output power dissipation	Po	75	mW
Output power dissipation derating (Ta ≥ 25°C)	ΔΡ _Ο /ΔΤ _a	-0.75	mW / °C
Junction Temperature	Fi	125	°C
ating Temperature Range	Topr	-40 to 100	°C
ge Temperature Range	Tstg	-55 to 125	°C
Solder Temperature (10 s)	Tsol	260	°C
ion Voltage (AC, 60 s, R.H. ≤ 60 %) (Note 2)	BVs	5000	Vrms
	Forward Current (Ta ≤ 83°C) Forward Current Derating (Ta ≥ 83°C) Peak Transient Forward Current (Note 1) Reverse Voltage Input power dissipation Input power dissipation derating (Ta ≥ 83°C) Junction Temperature Output Current 1 (Ta ≤ 25°C) Output Current 2 (Ta ≤ 100°C) Output Voltage Supply Voltage Output power dissipation Output power dissipation derating (Ta ≥ 25°C) Junction Temperature ating Temperature Range ge Temperature Range Solder Temperature (10 s)	Forward Current (Ta \leq 83°C)	Forward Current (Ta \leq 83°C)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Pulse width PW ≤ 1 μs, 300 pps.

Note 2: Device Considered a two terminal device: pins 1, 2 and 3 shorted together and pins 4, 5 and 6 shorted together.

Recommended Operating Conditions

CHARACTERISTIC	SYMBOL	MIN	TYP.	MAX	UNIT
Input Current, ON	IF (ON)	4.5	-	10	mA
Input Voltage, OFF	VF (OFF)	0	-	0.8	V
Supply Voltage (Note 1)	Vcc	4.5	-	20	V
Operating Temperature	T _{opr}	-40	-	100	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

Note 1: This item denotes operating ranges, not meaning of recommended operating conditions.



Electrical Characteristics (Unless otherwise specified, Ta = −40 to 100°C, V_{CC} = 4.5 to 20 V)

CHARACTERISTIC	SYMBOL	TEST CIRCUIT	CONDITION	MIN	TYP.	MAX	UNIT
Input forward voltage	VF	_	I _F = 5 mA, Ta = 25 °C	1.4	1.6	1.7	V
Temperature coefficient of forward voltage	ΔV _F /ΔTa	_	I _F = 5 mA	_	-2.0	-	mV/°C
Input reverse current	IR	ı	V _R = 5 V, Ta = 25 °C			10	μΑ
Input capacitance	CT	-	V = 0 V, f = 1 MHz, Ta = 25 °C	\ \	45	_	pF
Logic LOW output voltage	V _{OL}	Figure 1	I _{OL} = 3.5 mA , I _F = 5 mA	3	0.2	0.6	V
Logic HIGH output voltage (Note 1)	Vон	Figure 2	$I_{OH} = -2.6 \text{ mA},$ $VF = 0.8 \text{ V}$ $VCC = 4.5 \text{ V}$ $VCC = 20 \text{ V}$	2.7	3.5		> >
Logic LOW supply current	ICCL	Figure 3	I _F = 5 mA	-<>	V (C)	3.0	mA
Logic HIGH supply current	Іссн	Figure 4	VF = 0 V	-	7	3.0	mA
Logic LOW short circuit output current (Note 2)	IOSL	Figure 5	$V_{CC} = V_{O} = 5.5 \text{ V}$ $V_{CC} = V_{O} = 20 \text{ V}$	15	80		mA
Logic HIGH short circuit output current (Note 3)	losh	Figure 6	V _F = 0 V, V _{CC} = 5.5 V V _O = GND V _{CC} = 20 V	-10	-15 -20	_	mA
Input current logic LOW output	I _{FHL}	+	I _O = 3.5 mA, V _O < 0.6 V	<i>)</i>)_	0.4	3	mA
Input voltage logic HIGH output	VFLH	(-1)	$I_O = -2.6 \text{ mA}, V_O > 2.4 \text{ V}$	0.8	_	_	V
Input current hysteresis	IHYS)-	Vcc = 5 V	_	0.05	_	mA

Note: All typical values are at Ta = 25 °C, Vcc = 5 V unless otherwise specified.

Note 1: $V_{OH} = V_{CC} - V_O[V]$

Note 2: Duration of output short circuit time should not exceed 10 ms.

Note 3: A ceramic capacitor (0.1 µF) should be connected from pin 6 to pin 4 to stabilize the operation of the high gain linear amplifier. Failure to provide the bypassing may impair the switching property. The total lead length between capacitor and coupler should not exceed 1 cm.

Isolation Characteristics (Ta = 25°C)

CHARACTERISTIC	SYMBOL TEST CONDITION		MIN	TYP.	MAX	UNIT
Capacitance input to output	Cs (Note 1)	VS = 0 V, f = 1 MHz	_	1.0	_	pF
Isolation resistance	Rs (Note 1)	R.H. ≤ 60 %, Vs = 500 V	1×10 ¹²	10 ¹⁴	_	Ω
Isolation voltage	BVs (Note 1)	AC, 60 s	5000	_	_	V _{rms}

Note: This device is considered as a two-terminal device: Pins 1, 2 and 3 are shorted together, and pins 4, 5 and 6 are shorted together.



Switching Characteristics

(Unless otherwise specified, Ta = -40 to 100° C, $V_{CC} = 4.5$ to 20 V)

-	•			-				
CHARACTERISTIC	SYMBOL	TEST CIRCUIT	CONDITION	MIN	TYP.	MAX	UNIT	
Propagation delay time to logic HIGH output	tpLH		$I_F = 3 \rightarrow 0 \text{ mA}$	30	120	250	ns	
Propagation delay time to logic LOW output	t _{pHL}		$I_F = 0 \rightarrow 3 \text{ mA}$	30	120	250	ns	
Switching time dispersion between ON and OFF	tpHL- t _{pLH}	Figure 7, Figure 8	•	_			220	ns
Rise Time (10 – 90 %)	t _r		$I_F = 3 \rightarrow 0 \text{ mA}, V_{CC} = 5 \text{ V}$		30	1	ns	
Fall Time (90 – 10 %)	t _f		$I_F = 0 \rightarrow 3 \text{ mA}, V_{CC} = 5 \text{ V}$		30		ns	
Common-mode transient Immunity at HIGH level output	СМн	Figure C	$V_{CM} = 1000 V_{p-p}, I_F = 0 mA,$ $V_{CC} = 20 V, Ta = 25 °C$	10000			V/μs	
Common-mode transient Immunity at LOW level output	CML	Figure 9	$V_{CM} = 1000 V_{p-p}$, $I_F = 5 \text{ mA}$, $V_{CC} = 20 \text{ V}$, $T_a = 25 ^{\circ}\text{C}$	-10000		<u></u>	V/μs	

Note: All typical values are at Ta = 25 °C.

Figure 1: VOL TEST CIRCUIT

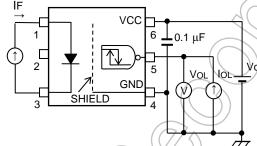


Figure 3: ICCL TEST CIRCUIT

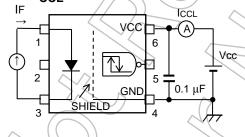


Figure 5: IOSL TEST CIRCUIT

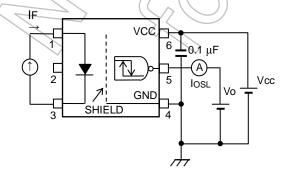


Figure 2: VOH TEST CIRCUIT

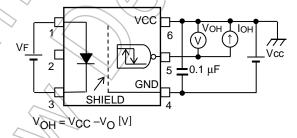


Figure 4: ICCH TEST CIRCUIT

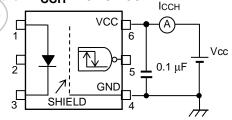


Figure 6: IOSH TEST CIRCUIT

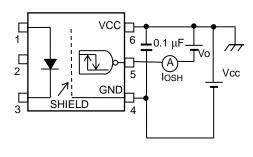
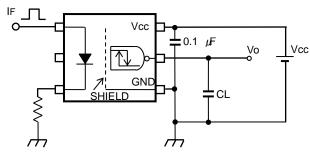


Figure 7: Switching Time Test Circuit

 $I_F = 3 \text{ mA(P.G)}$ (f = 50 kHz , duty = 50% less than tr = tf = 5ns)



CL: stray capacitance of probe and wiring (to 15 pF)

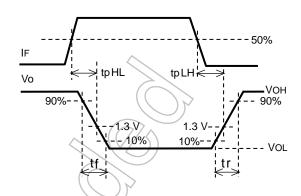
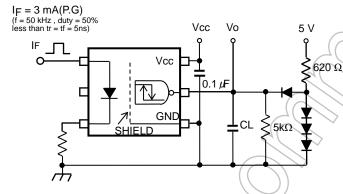


Figure 8: Switching Time Test Circuit



CL: stray capacitance of probe and wiring (to 15 pF)

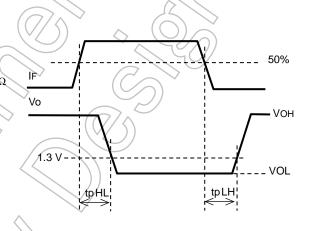
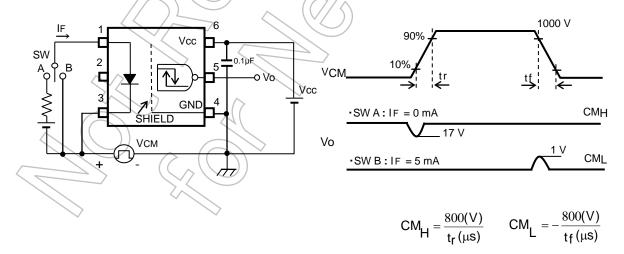


Figure 9: Common-Mode Transient Immunity Test Circuit



CM_H (CM_L) is the maximum rate of rise (fall) of the common mode voltage that can be sustained with the output voltage in the high (low) state.

EN 60747-5-5 Option:(D4)

Types :TLP718F

Type designations for "option: (D4)", which are tested under EN 60747 requirements.

Ex.: TLP718F (D4-TP,F) D4: EN 60747 option

TP: Standard tape & reel type/

F: [[G]]/RoHS COMPATIBLE (Note 1)

Note: Use TOSHIBA standard type number for safety standard application.

Ex.: TLP718F (D4-TP,F) → TLP718F

Note 1 : Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.

The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

EN 60747 Isolation Characteristics

Description		Symbol	Rating	Unit	
Application classification for rated mains voltage ≤ 300 V _{rms} for rated mains voltage ≤ 600 V _{rms}		I-IV I-III	_		
Climatic classification			40 / 100 / 21	_	
Pollution degree			2	_	
Maximum an arating inculation voltage	TLPxxx type	V/	890	Volc	
Maximum operating insulation voltage	TLPxxxF type	VIORM	1140	Vpk	
Input to output test voltage, method A	TLPxxx type		1424	Vpk	
Vpr = 1.6×Vorm, type and sample test tp = 10 s, partial discharge < 5 pC	TLPxxxF type	Vpr	1824		
Input to output test voltage, method B	TLPxxx type		1670	Vpk	
Vpr = $1.875 \times V_{IORM}$, 100% production test $t_p = 1$ s, partial discharge < 5 pC	TLPxxxF type	Vpr	2140		
Highest permissible overvoltage (transient overvoltage, t _{pr} = 60 s)		V _{TR}	8000	Vpk	
Safety limiting values (max permissible ratings in case of fault, also refer to thermal deration current (input current I_F , $P_{Si}=0$) power (output or total power dissipation) temperature	Isi Psi Tsi	300 700 150	mA mW °C		
Insulation resistance, $\begin{aligned} V_{IO} &= 500 \text{ V, Ta} = 25^{\circ}\text{C} \\ V_{IO} &= 500 \text{ V, Ta} = 100^{\circ}\text{C} \\ V_{IO} &= 500 \text{ V, Ta} = \text{Tsi} \end{aligned}$	Rsi	≥10 ¹² ≥10 ¹¹ ≥10 ⁹	Ω		



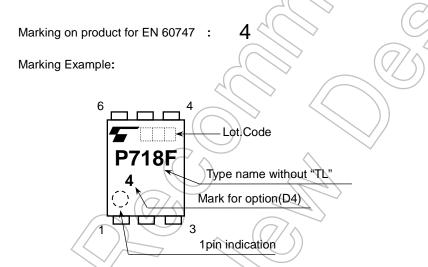
Insulation Related Specifications

		7.62 mm pitch TLPxxx type	10.16 mm pitch TLPxxxF type	
Minimum creepage distance	Cr	7.0 mm	8.0 mm	
Minimum clearance	CI	7.0 mm	8.0 mm	
Minimum insulation thickness	ti	0.4 mm		
Comperative tracking index	СТІ	17	5	

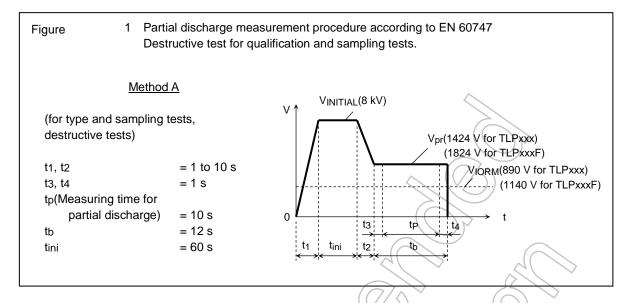
Note: If a printed circuit is incorporated, the creepage distance and clearance may be reduced below this value. If this is not permissible, the user shall take suitable measures.

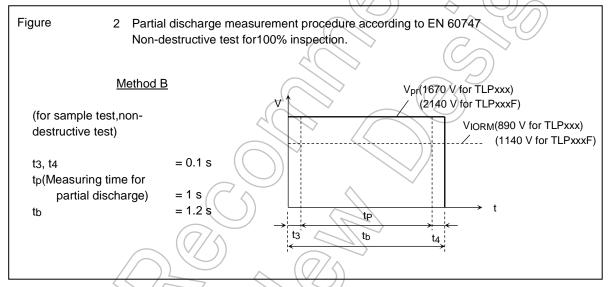
Note: This photocoupler is suitable for 'safe electrical isolation' only within the safety limit data.

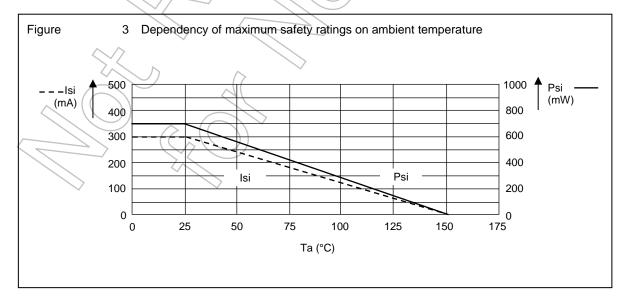
Maintenance of the safety data shall be ensured by means of protective circuits.



Note: The above marking is applied to the photocouplers that have been qualified according to option (D4) of EN 60747.







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